

# Effect of different sputter power on ITO/p-GaN and their interface investigations

藍志學、黃俊達

E-mail: 9509677@mail.dyu.edu.tw

## ABSTRACT

Interface and contact properties of Indium-tin-oxide (ITO) on p-GaN has been investigated, in which ITO was deposited by RF sputtering with different power. It is found that with increasing of sputtering power, the nitrogen vacancies increase on the surface of p-GaN by using Auger electron spectroscopy (AES). The nitrogen vacancy will act as a donor and thus increase the electron concentration between ITO and p-GaN interface. The increase in electron concentration will compensate the holes of p-GaN films therefore the contact resistance of ITO to p-GaN will increase as a result of the decreasing of concentrations in p-GaN. While increasing sputtering power further, the electron concentration of surface below ITO will increase further and then the surface of p-GaN will be inverted into n-type. This phenomenon will be confirmed by using current-voltage (I-V) characteristics, in which the I-V curve transfers from quasi-ohmic to rectifying behavior. Following, the ITO/p-GaN devices were annealed in rapid thermal annealing (RTA) system with temperature ranging from 600 to 800 under nitrogen ambient. In 800 annealing temperature, the I-V curve transfers from rectifying to quasi-ohmic. Possible reason is that the nitrogen vacancies below the ITO surface are compensated.

Keywords : GaN, Indium-tin-oxide, sputter

## Table of Contents

目錄 封面內頁 簽名頁 授權書 . . . . .	iii	中文摘要 . . . . .	iii
. . . . . iv 英文摘要 . . . . .	iv	v 誌謝 . . . . .	v
. . . . . vi 目錄 . . . . .	vi	vii 圖目錄 . . . . .	vii
. . . . . ix 表目錄 . . . . .	ix		
. xi 第一章 緒論 . . . . .	1	第二章 基本理論 . . . . .	1
. . . . . 4 2.1 金屬/半導體接觸之原理 . . . . .	4	4 2.2 銻錫氧化物之電性 . . . . .	4
. . . . . 7 2.3 濺鍍原理 . . . . .	7	8 2.4 電漿原理 . . . . .	8
. . . . . 8 2.5 薄膜沉積原理 . . . . .	8	10 第三章 實驗方法及量測 . . . . .	10
. . . . . 11 3.1 ITO薄膜製膜參數及步驟 . . . . .	11	11 3.1.1 鍍膜參數 . . . . .	11
. . . . . 11 3.1.2 玻璃基板清洗 . . . . .	11	12 3.2 ITO薄膜品質的量測與分析 . . . . .	12
. . . . . 12 3.2.1 膜厚度量測 . . . . .	12	12 3.2.2 X-Ray繞射分析 . . . . .	12
. . . . . 13 3.2.3 光學穿透率 . . . . .	13	14 3.2.4 表面平坦度量測 . . . . .	14
3.2.5 電阻矽數量測 . . . . .	15	15 3.3 氮化鎵薄膜之製備 . . . . .	15
3.4 金屬接觸之製作 . . . . .	16	16 3.4.1 p型氮化鎵基板清洗 . . . . .	16
. . . . . 16 3.4.2 歐姆接觸沉積及熱處理 . . . . .	16	17 3.4.3 ITO金屬沉積及熱處理 . . . . .	17
. . . . . 18 3.5 實驗量測 . . . . .	18	18 3.5.1 電性量測 . . . . .	18
. . . . . 18 3.5.2 AES縱深分析 . . . . .	18	19 第四章 結果與討論 . . . . .	19
. . . . . 20 4.1歐姆接觸電性量測結果 . . . . .	20	20 4.2 ITO薄膜厚度、穿透率及電阻係數量	20
測結果 . . . . .	20	20 4.3沒經過熱處理在不同濺射功率鍍上ITO/p-GaN 電性之 影響 . . . . .	20
. . . . . 22 4.4熱處理對ITO/p-GaN之影響 . . . . .	22	23 第五章 結論 . . . . .	23
. . . . . 25 參考文獻 . . . . .	25	45 圖目錄 圖2-1 金屬與n型半導體接觸能帶圖	45
. . . . . 26 圖2-2 金屬/半導體界面之電流傳輸機制 . . . . .	26	28 圖3-1 -step量測方式示	28
意圖 . . . . .	29	29 圖3-2 X光繞射儀裝置圖 . . . . .	29
30 圖3-3 PC量測實驗裝置圖 . . . . .	30	30 圖3-4 元件結構圖 . . . . .	30
. . . . . 30 圖4-1 Ni/Au(5nm/5nm)改變不同退火溫度I-V圖 . . . . .	31	31 圖4-2 Ni/Au(5nm/5nm)改變不同退火時間的I-V圖	31
. . . . . 31 圖4-3不同?射功率下的沉積速率圖 . . . . .	31	32 圖4-4 RF=140W時的AFM 3D圖 . . . . .	32
. . . . . 32 圖4-5 RF=160W時的AFM 3D圖 . . . . .	32	33 圖4-6 RF=180W時的AFM 3D圖 . . . . .	33
. . . . . 33 圖4-7 RF=200W時的AFM 3D圖 . . . . .	33	34 圖4-8不同濺射功率下	34
的RMS值比較 . . . . .	34	34 圖4-9不同?射功率下的穿透率圖 . . . . .	34
. . . . . 35 圖4-10不同功率	35		

下的XRD分析比較圖 . . . . . 35 圖4-11不同濺射功率下I(222)/I(400)的比值 . . . . . 36  
圖4-12不同功率下的電阻係數比較圖 . . . . . 36 圖4-13不同?射功率的ITO在沒退火下的I-V圖 . . . . . 37  
. . . . . 37 圖4-14不同?射功率在沒退火時的漏電流比較 . . . . . 37 圖4-15 RF=140W時的AES縱深分析 . . . . . 38  
. . . . . 38 圖4-16 RF=160W時的AES縱深分析 . . . . . 38 圖4-17 RF=180W時的AES縱深分析 . . . . . 39  
圖4-18 RF=200W時的AES縱深分析 . . . . . 39 圖4-19不同濺射功率下時的Ga/N比例 . . . . . 40 圖4-20固定RF=140W時, 比較有無熱處理的I-V圖 . . . . . 40  
圖4-21固定RF=160W時, 比較有無熱處理的I-V圖 . . . . . 41 圖4-22固定RF=180W時, 比較有無熱處理的I-V圖 . . . . . 41  
圖4-23固定RF=200W時, 比較有無熱處理的I-V圖 . . . . . 42 圖4-24固定RF=140W時, 比較有無經過熱處理之後的漏電流比較 . . . . . 42  
圖4-25固定RF=160W時, 比較有無經過熱處理之後的漏電流比較 . . . . . 43  
圖4-26固定RF=180W時, 比較有無經過熱處理之後的漏電流比較 . . . . . 43  
圖4-27固定RF=200W時, 比較有無經過熱處理之後的漏電流比較 . . . . . 43  
. . . . . 44 表目錄 表一. 各種金屬材料之功函數 . . . . . 32 表二. ITO薄膜參數 . . . . . 27

REFERENCES

[1] S. Nakamura and G. Fasol, *The Blue Laser Diodes*, Springer Heidelberg (1997).  
[2] S. Nakamura, T. Mukai, and M. Senoh, “Candela-class high-brightness InGaN/AlGaIn double-heterostructure blue-light-emitting diodes”, *Appl. Phys. Lett.* Vol.64, p.1687 (1994).  
[3] S. Nakamura, M. Senoh, N. Iwasa, S. Nagahama, T. Yamada, and T. Mukai, “Superbright Green InGaIn Single-Quantum-Well-Structure Light-Emitting Diode”, *Jap. J. Appl. Phys.* Vol.34, p.L1332(1995).  
[4] T. Mukai, D. Morita, and S. Nakamura, “High-power UV InGaIn/AlGaIn double-heterostructure LEDs”, *J. Cryst. Growth*, Vol.189/190, p.778(1998).  
[5] T. Mukai, H. Narimatsu, and S. Nakamura, “Amber InGaIn-Based Light-Emitting Diodes Operable at High Ambient Temperature”, *Jan. J. Appl. Phys.* Vol.37, p.L479(1998).  
[6] M. S. Shur, “GaN Based Transistors for High Power Applications”, *Solid-State Electronics*, Vol.42, p.2131(1998).  
[7] M. A. Khan, J. N. Kuznia, A. R. Bhattarai, and D. T. Olson, “Metal semiconductor field effect transistor based on single crystal GaN”, *Appl. Phys. Lett.* Vol. 62, p.1786 (1993).  
[8] M. A. Khan, J. N. Kuznia, D. T. Olson, W. J. Schaff, J. W. Burm, and M. S. Shur, “Microwave performance of a 0.25um gate AlGaIn/GaN heterostructure field effect transistor”, *Appl. Phys. Lett.* Vol. 64, p.1121 (1994).  
[9] F. Ren, C. R. Abernathy, J. M. Van Hove, P. P. Chow, R. Hickman, J. J. Klaasen, R. F. Kopf, H. Cho, K. B. Jung, J. R. La Roche, R. G. Wilson, J. Han, R. J. Shul, A. G. Baca, and S. J. Pearton, “300 GaIn/AlGaIn Heterojunction Bipolar Transistor”, *MRS Internet J. Nitride Semicond. Res.* Vol.3,41(1998).  
[10] G. S. Nakamura, “InGaIn-based violet laser diodes”, *Semicond. Sci. Technol.* Vol.14, p.R27(1999).  
[11] M. A. Khan, J. N. Kuznia, D. T. Olson, M. Blasingame, and A. R. Bhattarai, “Schottky barrier photodetector based on Mg-doped p-type GaN film”, *Appl. Phys. Lett.* Vol.63, p.2455(1993).  
[12] S. Strite and H. Morkoc, *J. Vac. Sci. Technol.* B10, 1237 (1992).  
[13] M. Asif Khan, J. N. Kuznia, D. T. Olson, J. M. Van hove, M. Blasingame, L. F. Reitz, “High-responsivity photoconductive ultraviolet sensors based on insulating single-crystal GaIn epilayers”, *Appl. Phys. Lett.* Vol.60, p.2917(1992).  
[14] Z. C. Huang, D. B. Mott, P. K. Shu, R. Zhang, J. C. Chen, D. K. Wickenden, “Optical quenching of photoconductivity in GaIn photoconductors”, *J. Appl. Phys.* Vol.82, p.2707(1997).  
[15] J. C. Carrano, T. Li, P. A. Grudowski, C. J. Eiting, R. D. Dupuis, J. C. Campell, “Comprehensive characterization of metal-semiconductor-metal ultraviolet photodetectors fabricated on single-crystal GaIn”, *J. Appl. Phys.* Vol.83, p.6148(1995).  
[16] Q. Chen, M. A. Khan, C. J. Sun, and J. W. Yang, “Visible-blind ultraviolet photodetectors based on GaIn p-n junctions”, *Electron. Lett.* Vol.31, p.1781(1995).  
[17] E. Monroy, E. Munoz, F. J. Sanchez, F. Calle, E. Calleja, B. Beaumont, P. Gibart, J. A. Munoz, F. Cusso, “High-performance GaIn p-n junction photodetectors for solar ultraviolet applications”, *Semicond. Sei. Technol.* Vol.13, p.1042(1998).  
[18] D. Walker, A. Saxler, P. Kung, X. Zhang, M. Hamilton, D. Jiaz, M. Razeghi, “Visible blind GaIn p-i-n photodiodes”, *Appl. Phys. Lett.* Vol.72, p.3303(1998).  
[19] E. Monroy, M. Hamilton, D. Walker, P. Kung, F. J. San-chez, M. Razeghi, “High-quality visible-blind AlGaIn p-i-n photodiodes”, *Appl. Phys. Lett.* Vol.74, p.1171(1999).  
[20] E. Monroy, F. Calle, E. Munoz, F. Omnes, P. Gibart, J. A. Munoz, “AlxGa1-xN:Si Schottky barrier photodiodes with fast response and high

detectivity ” , Appl. Phys. Lett. Vol.73, p.2146(1998).

- [21] D. Walker, E. Monroy, P. Kung, J. Wu, M. Hamilton, F. J. Sanchez, J. Diaz, M. Razeghi, “ High-speed, low-noise metal-semiconductor-metal ultraviolet photodetectors based on GaN ” , Appl. Phys. Lett. Vol.74, p.762(1999) [22] E. Monroy, F. Calle, E. Munoz, and F. Omnes, “ Effects of Bias on the Responsivity of GaN Metal-Semiconductor-Metal Photodiodes ” , Phys. Stat. Sol. (a), Vol.176, p.157(1999).
- [23] H. Jiang, N. Nakata, G. Y. Zhao, H. Ishikawa, C. L. Shao, T. Egawa, T. Jimbo, M. Umeno, “ Back-Illuminated GaN Metal-Semiconductor-Metal UV Photodetector with High Internal Gain ” , Jap. J. Appl. Phys. Vol.40, p.L505(2001).
- [24] C. H. Chen, S. J. Chang, Y. K. Su, Senior Member, IEEE, G. C. Chi, J. Y. Chi, C. A. Chang, J. K. Sheu, and J. F. Chen, Member, “ GaN metal-semiconductor-metal ultraviolet photodetectors with transparent indium-tin-oxide Schottky contacts ” , IEEE photon. Technol. Lett. Vol.13, p.848(2001).
- [25] H. Z. Xu, Z. G. Wang, M. Kawabe, I. Harrison, B. J. Ansell, C. T. Foxon, “ Fabrication and characterization of metal-semiconductor-metal (MSM) ultraviolet photodetectors on undoped GaN/sapphire grown by MBE ” , J. Crystal. Growth, Vol.218, p.1(2000).
- [26] L. S. Yu, D. Qiao, L. Jia, S. S. Lau, Y. Qi, and K. M. Lau, Appl. Phys. Lett. 79, 4536(2001).
- [27] S. Y. Kim, H. W. Jang, and J. L. Lee, Appl. Phys. Lett. 82, 61(2003).
- [28] N. Biyikli, T. Kartaloglu, O. Aytur, I. Kimukin, and E. Ozbay, Appl. Phys. Lett. 79, 2838(2001).
- [29] T. Margalith, O. Buchinsky, D. A. Cohen, A. C. Abare, M. Hansen, S. P. DenBaars, and L. A. Coldren, Appl. Phys. Lett. 74, 3930(1999).
- [30] D. W. Kima,\*, Y. J. Sunga, J. W. Parkb, G. Y. Yeoma, Thin Solid Films 398 – 399 (2001) 87 – 92 [31] J. K. Sheu, Y. K. Su, G. C. Chi, M. J. Jou, and C. M. Chang , Appl. Phys. Lett. 72, 3317(1998).
- [32] X. A. Cao, S. J. Peartona), A. P. Zhang, G. T. Dang, and F. Ren, R. J. Shul and L. Zhang, R. Hickman and J. M. Van Hove, Appl. Phys. Lett. Vol.75,p.2569 (1999) [33] X. A. Cao, S. J. Pearton, Senior Member, IEEE, G. T. Dang, A. P. Zhang, F. Ren, and J. M. Van Hove, TRANSACTIONS ON ELECTRON DEVICES ,IEEE, VOL. 47, NO. 7, JULY 2000 [34] F. Braun, Annal. Phys. Chem. 153, 556 (1874).
- [35] W. Schottky, Naturwissenschaften 26, 843 (1938).
- [36] J. K. Sheu ,Y. K. Su, G. C. Chia), W. C. Chen, C. Y. Chen, C. N. Huang, and J. M. Hong, Y. C. Yu, C. W. Wang, and E. K. Lin,J. Appl. Phy. Lett. Vol.83, p.3172 (1998).
- [37] Jin-Kuo Ho,a) Charng-Shyang Jong, Chien C. Chiu, Chao-Nien Huang, and Kwang-Kuo Shih, J. Appl. Phys. Lett. Vol.86, p.4491 (1999).
- [38] M. Hanzaz and A. Bouhdadaa), P. Gibart and F. Omne`s, J. Appl. Phys. Lett. Vol.92, p.13 (2002).
- [39] K.N. Lee a, X.A. Cao a, C.R. Abernathy a,\*, S.J. Pearton a, A.P. Zhang b, F. Ren b,R. Hickman c, J.M. Van Hove c, Solid-State Electronics 44 (2000) 1203 ± 1208 [40] X. A. Cao, H. Cho, and S. J. Pearton, G. T. Dang, A. P. Zhang, and F. Ren, R. J. Shul and L. Zhang, R. Hickman and J. M. Van Hove, Appl. Phys. Lett. Vol.75,p.232 (1999) [41] D.G. Kent a, K.P. Lee a, A.P. Zhang b, B. Luo b, M.E. Overberg a, C.R. Abernathy a, F.Ren b,\*, K.D. Mackenzie c, S.J. Pearton a, Y. Nakagawa d, Solid-State Electronics 45(2001) 467-470 [42] L. S. Yu, L. Jia, D. Qiao, S. S. Lau, J. Li, J. Y. Lin, and H. X. Jiang, TRANSACTIONS ON ELECTRON DEVICES ,IEEE, VOL. 50, NO.2, FEBRUARY2003 [43] D.L. Pulfrey a,\*, G. Parish b, D. Wee b, B.D. Nener b, Solid-State Electronics 49(2005) 1969-1973 [44] Yow-Jon Lina! and Yow-Lin Chu, J. Appl. Phys. Lett. Vol.97, p.104904 (2005).
- [45] Z.Z. Chen\*, Z.X. Qin, Y.Z. Tong, X.M. Ding, X.D. Hu, T.J. Yu, Z.J. Yang,G.Y. Zhang, Physica B 334 (2003) 188 – 192 [46] Z.X. Qina,\*, Z.Z. Chena, H.X. Zhanga,b, X.M. Dinga, X.D. Hua, T.J. Yua,Y.Z. Tonga, G.Y. Zhanga, Materials Science in Semiconductor Processing 5 (2003) 473 – 475